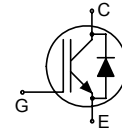


Low Loss DuoPack : IGBT in TrenchStop® and Fieldstop technology  
 with soft, fast recovery anti-parallel EmCon HE diode

Very low  $V_{CE(sat)}$  1.5 V (typ.)

- Maximum Junction Temperature 175 °C
- Short circuit withstand time – 5µs
- Designed for :
  - Frequency Converters
  - Drives
- TrenchStop® and Fieldstop technology for 600 V applications offers :
  - very tight parameter distribution
  - high ruggedness, temperature stable behavior
  - very high switching speed
  - low  $V_{CE(sat)}$
- Positive temperature coefficient in  $V_{CE(sat)}$
- Low EMI
- Low Gate Charge
- Very soft, fast recovery anti-parallel EmCon HE diode
- Qualified according to JEDEC<sup>1</sup> for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>



Type	$V_{CE}$	$I_C$	$V_{CE(sat), T_j=25^\circ C}$	$T_{j,max}$	Marking	Package
IKP04N60T	600 V	4 A	1.5 V	175 °C	K04T60	PG-TO-220-3-1
IKI04N60T	600 V	4 A	1.5 V	175 °C	K04T60	PG-TO-262-3

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CE}$	600	V
DC collector current, limited by $T_{j,max}$ $T_C = 25^\circ C$ $T_C = 100^\circ C$	$I_C$	8 4	A
Pulsed collector current, $t_p$ limited by $T_{j,max}$	$I_{C,puls}$	12	
Turn off safe operating area ( $V_{CE} \leq 600V, T_j \leq 175^\circ C$ )	-	12	
Diode forward current, limited by $T_{j,max}$ $T_C = 25^\circ C$ $T_C = 100^\circ C$	$I_F$	8 4	
Diode pulsed current, $t_p$ limited by $T_{j,max}$	$I_{F,puls}$	12	
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Short circuit withstand time <sup>2)</sup> $V_{GE} = 15V, V_{CC} \leq 400V, T_j \leq 150^\circ C$	$t_{SC}$	5	µs
Power dissipation $T_C = 25^\circ C$	$P_{tot}$	42	W
Operating junction temperature	$T_j$	-40...+175	°C
Storage temperature	$T_{stg}$	-55...+175	
Soldering temperature, 1.6mm (0.063 in.) from case for 10s	-	260	

<sup>1</sup> J-STD-020 and JEDEC-022

<sup>2)</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

**Thermal Resistance**

Parameter	Symbol	Conditions	Max. Value	Unit
<b>Characteristic</b>				
IGBT thermal resistance, junction – case	$R_{thJC}$		3.5	K/W
Diode thermal resistance, junction – case	$R_{thJCD}$		5	
Thermal resistance, junction – ambient	$R_{thJA}$		62	

**Electrical Characteristic, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
<b>Static Characteristic</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=0.2mA$	600	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=4A$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$	- -	1.5 1.9	2.05 -	
Diode forward voltage	$V_F$	$V_{GE}=0V, I_F=4A$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$	- -	1.65 1.6	2.05 -	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 60\mu A, V_{CE} = V_{GE}$	4.1	4.9	5.7	
Zero gate voltage collector current	$I_{CES}$	$V_{CE}=600V,$ $V_{GE}=0V$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$	- -	- -	40 1000	$\mu\text{A}$
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0V, V_{GE}=20V$	-	-	100	
Transconductance	$g_{fs}$	$V_{CE}=20V, I_C=4A$	-	2.2	-	S
Integrated gate resistor	$R_{Gint}$			-		$\Omega$

**Dynamic Characteristic**

Input capacitance	$C_{iss}$	$V_{CE}=25V,$	-	252	-	pF
Output capacitance	$C_{oss}$	$V_{GE}=0V,$	-	20	-	
Reverse transfer capacitance	$C_{riss}$	$f=1MHz$	-	7.5	-	
Gate charge	$Q_{Gate}$	$V_{CC}=480V, I_C=4A$ $V_{GE}=15V$	-	27	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	$L_E$		-	7	-	nH
Short circuit collector current <sup>1)</sup>	$I_{C(SC)}$	$V_{GE}=15V, t_{SC}\leq 5\mu s$ $V_{CC}=400V,$ $T_j\leq 150^\circ\text{C}$	-	36	-	A

<sup>1)</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

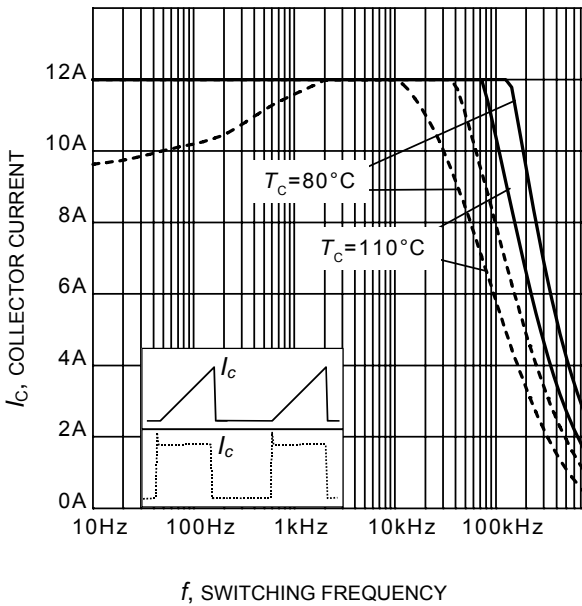
**Switching Characteristic, Inductive Load, at  $T_j=25^\circ\text{C}$** 

Parameter	Symbol	Conditions	Value			Unit	
			min.	Typ.	max.		
<b>IGBT Characteristic</b>							
Turn-on delay time	$t_{d(on)}$	$T_j=25^\circ\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=4\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=47\ \Omega$ , $L_{\sigma}^{1)}=150\text{nH}$ , $C_{\sigma}^{1)}=47\text{pF}$ Energy losses include "tail" and diode reverse recovery.	-	14	-	ns	
Rise time	$t_r$		-	7	-		
Turn-off delay time	$t_{d(off)}$		-	164	-		
Fall time	$t_f$		-	43	-		
Turn-on energy	$E_{on}$		Energy losses include "tail" and diode reverse recovery.	-	61	-	$\mu\text{J}$
Turn-off energy	$E_{off}$			-	84	-	
Total switching energy	$E_{ts}$			-	145	-	
<b>Anti-Parallel Diode Characteristic</b>							
Diode reverse recovery time	$t_{rr}$	$T_j=25^\circ\text{C}$ , $V_R=400\text{V}$ , $I_F=4\text{A}$ , $di_F/dt=610\text{A}/\mu\text{s}$	-	28	-	ns	
Diode reverse recovery charge	$Q_{rr}$		-	79	-	nC	
Diode peak reverse recovery current	$I_{rrm}$		-	5.3	-	A	
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	346	-	$\text{A}/\mu\text{s}$	

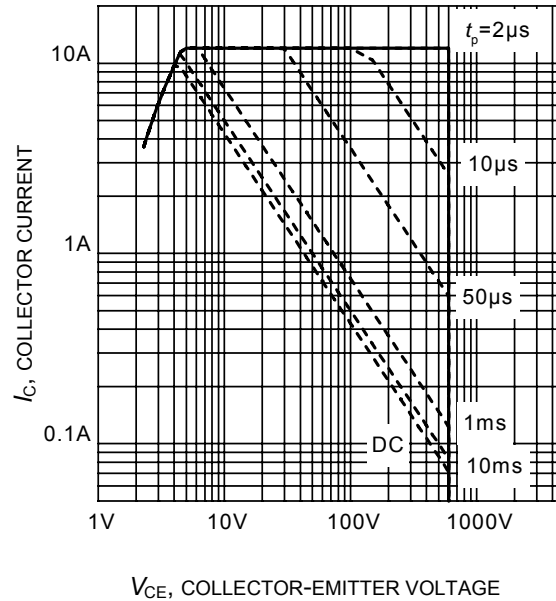
**Switching Characteristic, Inductive Load, at  $T_j=175^\circ\text{C}$** 

Parameter	Symbol	Conditions	Value			Unit	
			min.	Typ.	max.		
<b>IGBT Characteristic</b>							
Turn-on delay time	$t_{d(on)}$	$T_j=175^\circ\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=4\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=47\ \Omega$ , $L_{\sigma}^{1)}=150\text{nH}$ , $C_{\sigma}^{1)}=47\text{pF}$ Energy losses include "tail" and diode reverse recovery.	-	14	-	ns	
Rise time	$t_r$		-	10	-		
Turn-off delay time	$t_{d(off)}$		-	185	-		
Fall time	$t_f$		-	83	-		
Turn-on energy	$E_{on}$		Energy losses include "tail" and diode reverse recovery.	-	99	-	$\mu\text{J}$
Turn-off energy	$E_{off}$			-	97	-	
Total switching energy	$E_{ts}$			-	196	-	
<b>Anti-Parallel Diode Characteristic</b>							
Diode reverse recovery time	$t_{rr}$	$T_j=175^\circ\text{C}$ , $V_R=400\text{V}$ , $I_F=4\text{A}$ , $di_F/dt=610\text{A}/\mu\text{s}$	-	95	-	ns	
Diode reverse recovery charge	$Q_{rr}$		-	291	-	nC	
Diode peak reverse recovery current	$I_{rrm}$		-	6.6	-	A	
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	253	-	$\text{A}/\mu\text{s}$	

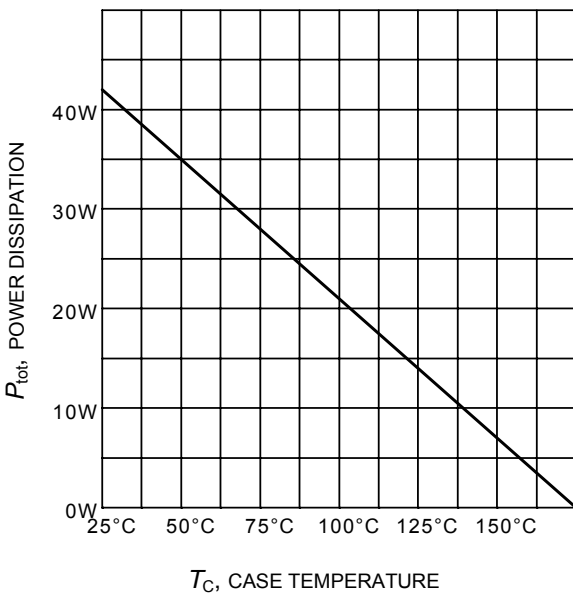
 1) Leakage inductance  $L_{\sigma}$  and Stray capacity  $C_{\sigma}$  due to dynamic test circuit in Figure E.



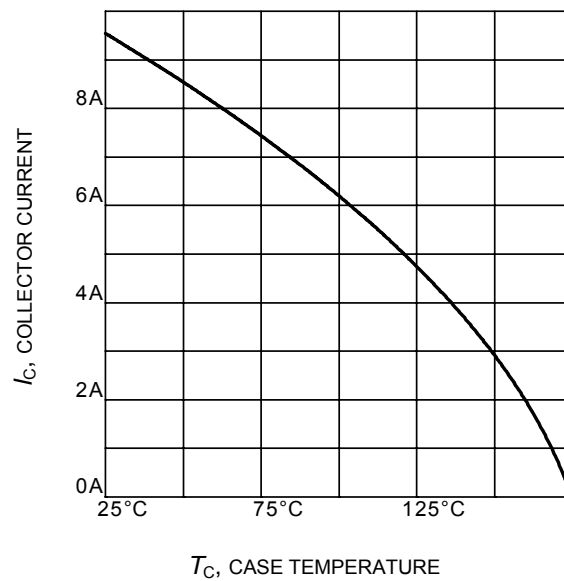
**Figure 1. Collector current as a function of switching frequency**  
( $T_j \leq 175^\circ\text{C}$ ,  $D = 0.5$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  $R_G = 47\Omega$ )



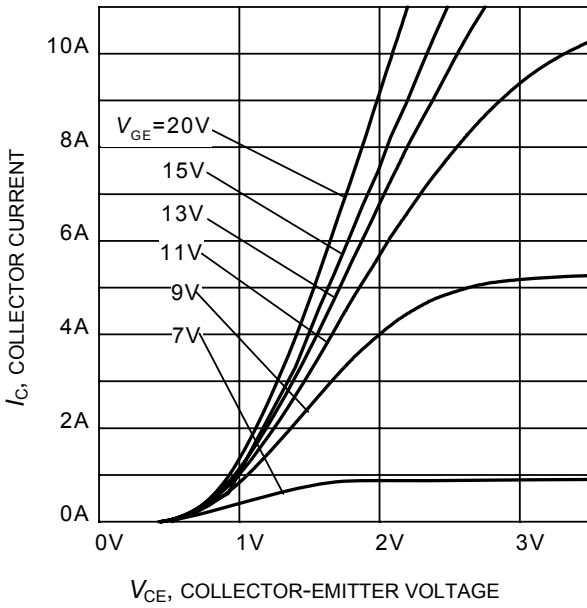
**Figure 2. Safe operating area**  
( $D = 0$ ,  $T_C = 25^\circ\text{C}$ ,  $T_j \leq 175^\circ\text{C}$ ;  $V_{GE} = 15\text{V}$ )



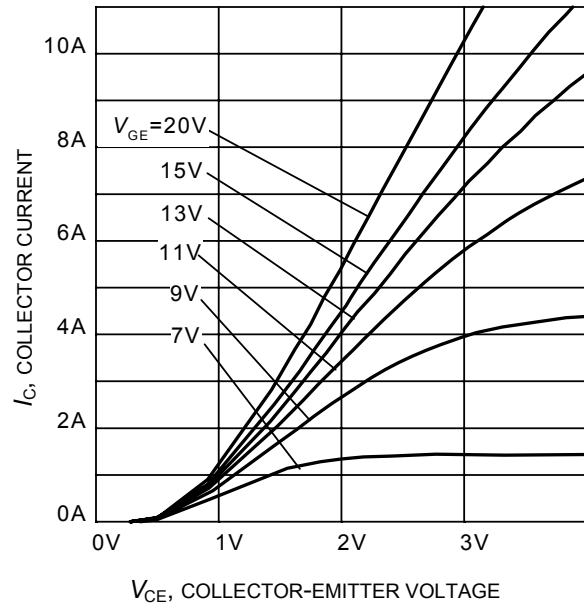
**Figure 3. Power dissipation as a function of case temperature**  
( $T_j \leq 175^\circ\text{C}$ )



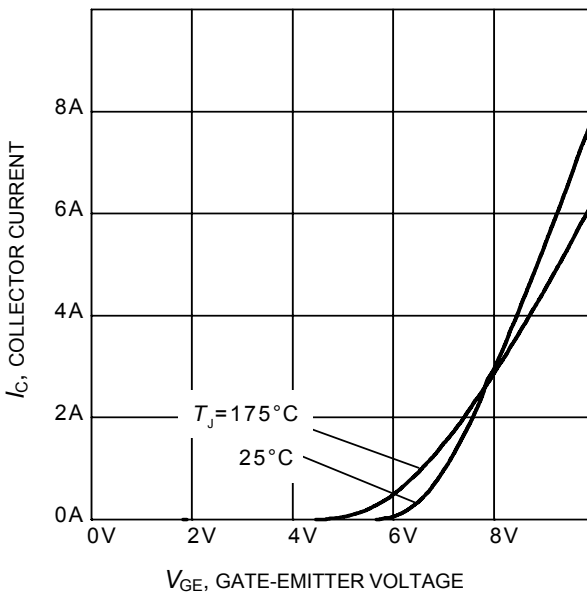
**Figure 4. Collector current as a function of case temperature**  
( $V_{GE} \geq 15\text{V}$ ,  $T_j \leq 175^\circ\text{C}$ )



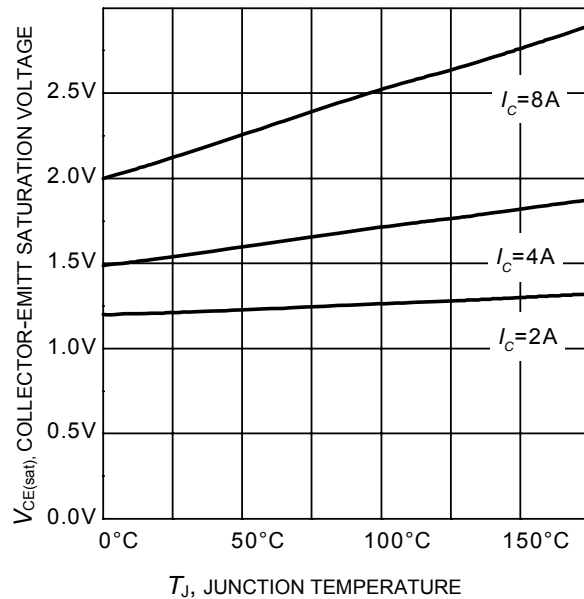
**Figure 5. Typical output characteristic**  
( $T_J = 25^\circ\text{C}$ )



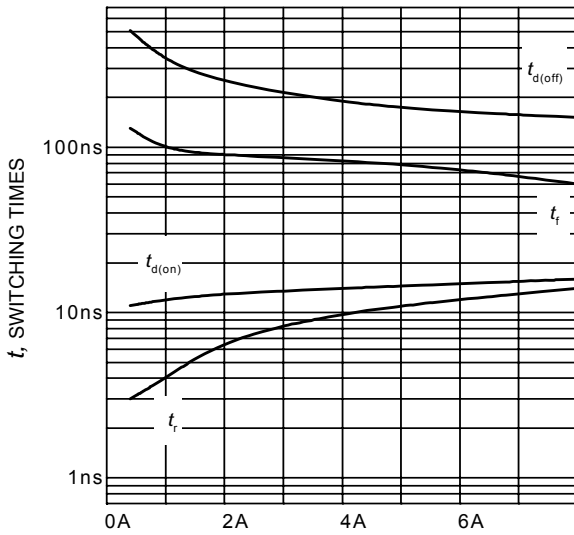
**Figure 6. Typical output characteristic**  
( $T_J = 175^\circ\text{C}$ )



**Figure 7. Typical transfer characteristic**  
( $V_{CE} = 20\text{V}$ )

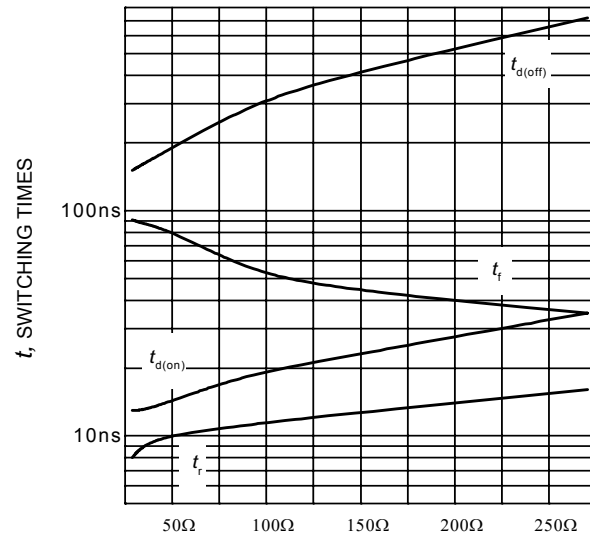


**Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature**  
( $V_{GE} = 15\text{V}$ )



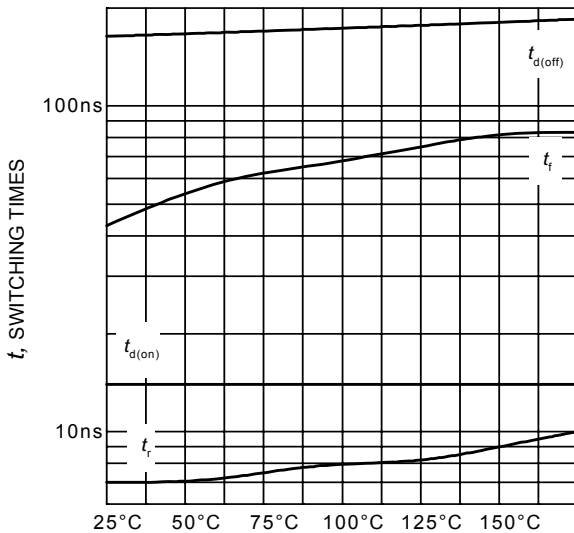
$I_C$ , COLLECTOR CURRENT

**Figure 9. Typical switching times as a function of collector current**  
(inductive load,  $T_J=175^\circ\text{C}$ ,  
 $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $R_G = 47\Omega$ ,  
Dynamic test circuit in Figure E)



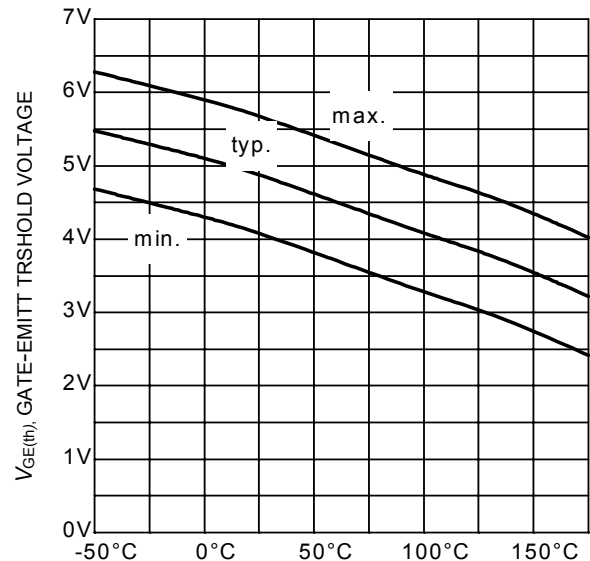
$R_G$ , GATE RESISTOR

**Figure 10. Typical switching times as a function of gate resistor**  
(inductive load,  $T_J = 175^\circ\text{C}$ ,  
 $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 4\text{A}$ ,  
Dynamic test circuit in Figure E)



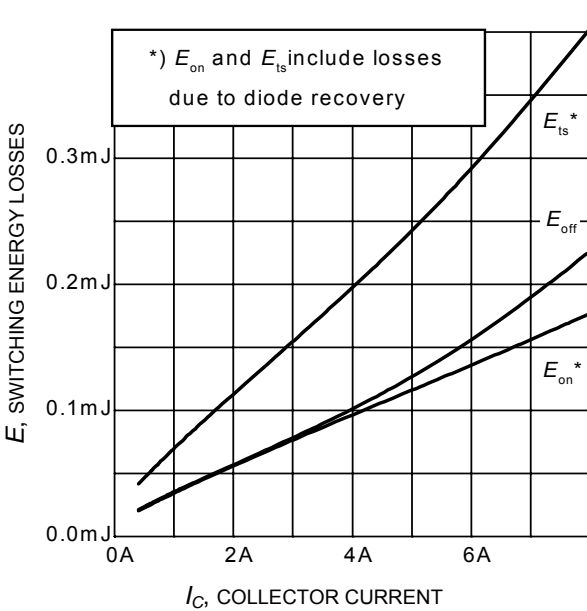
$T_J$ , JUNCTION TEMPERATURE

**Figure 11. Typical switching times as a function of junction temperature**  
(inductive load,  $V_{CE} = 400\text{V}$ ,  
 $V_{GE} = 0/15\text{V}$ ,  $I_C = 4\text{A}$ ,  $R_G=47\Omega$ ,  
Dynamic test circuit in Figure E)

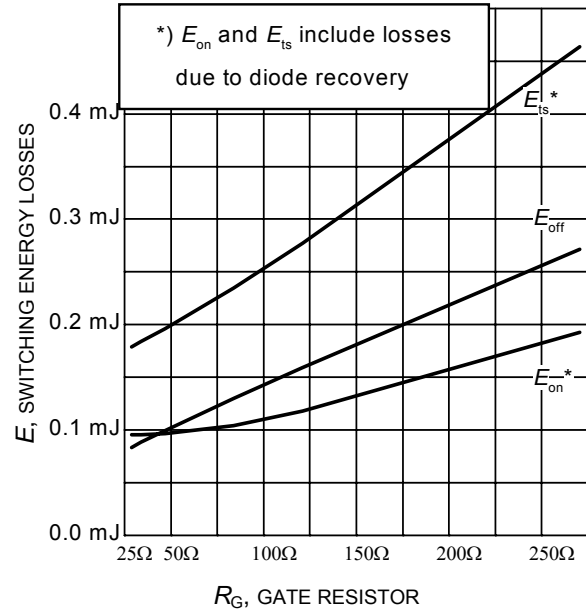


$T_J$ , JUNCTION TEMPERATURE

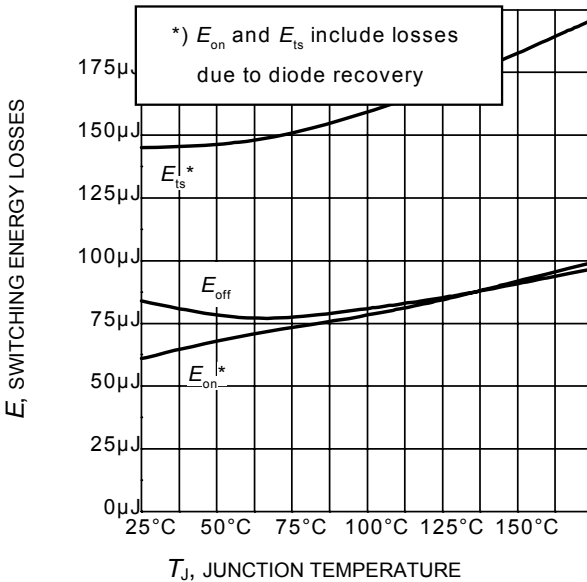
**Figure 12. Gate-emitter threshold voltage as a function of junction temperature**  
( $I_C = 60 \mu\text{A}$ )



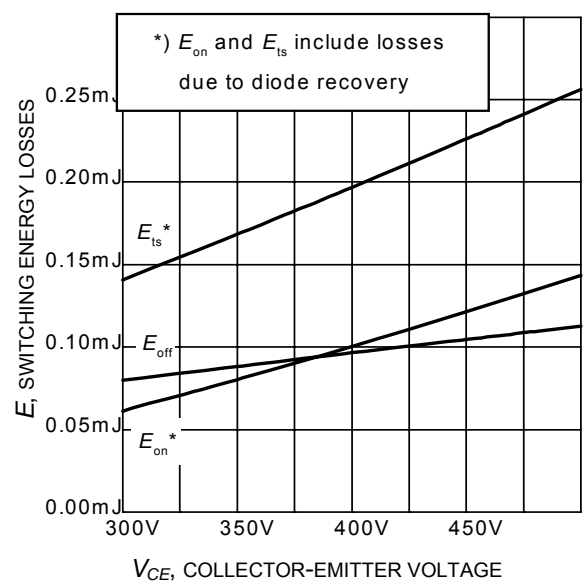
**Figure 13. Typical switching energy losses as a function of collector current**  
(inductive load,  $T_J = 175^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $R_G = 47\Omega$ , Dynamic test circuit in Figure E)



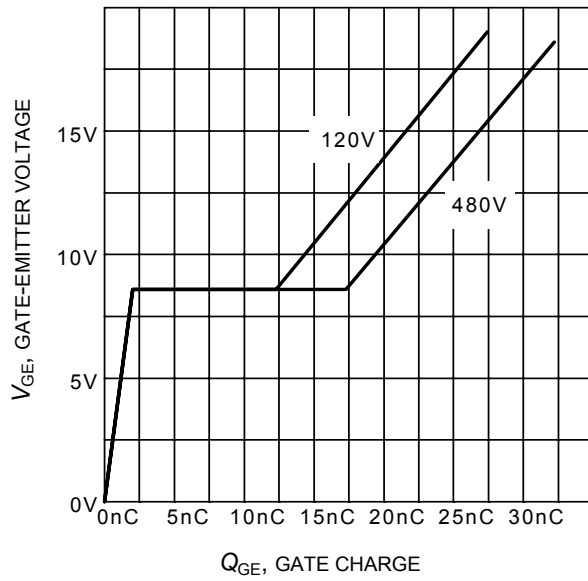
**Figure 14. Typical switching energy losses as a function of gate resistor**  
(inductive load,  $T_J = 175^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 4\text{A}$ , Dynamic test circuit in Figure E)



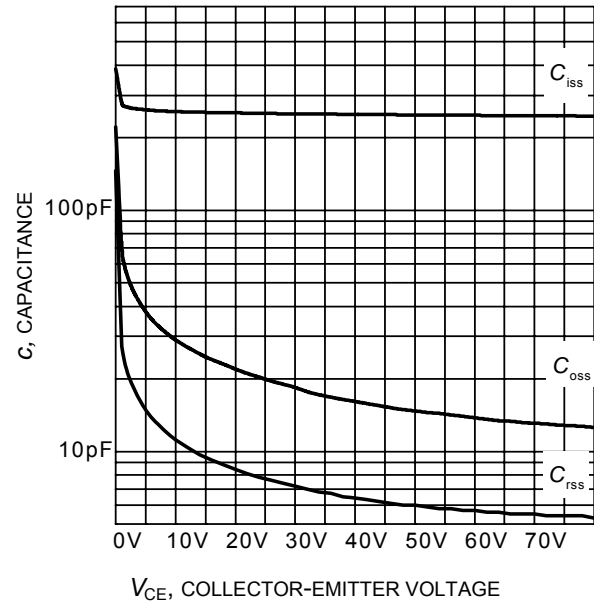
**Figure 15. Typical switching energy losses as a function of junction temperature**  
(inductive load,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 4\text{A}$ ,  $R_G = 47\Omega$ , Dynamic test circuit in Figure E)



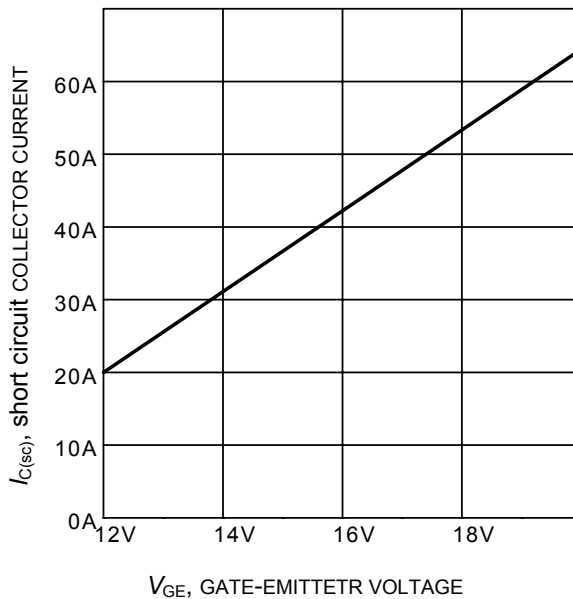
**Figure 16. Typical switching energy losses as a function of collector emitter voltage**  
(inductive load,  $T_J = 175^\circ\text{C}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 4\text{A}$ ,  $R_G = 47\Omega$ , Dynamic test circuit in Figure E)



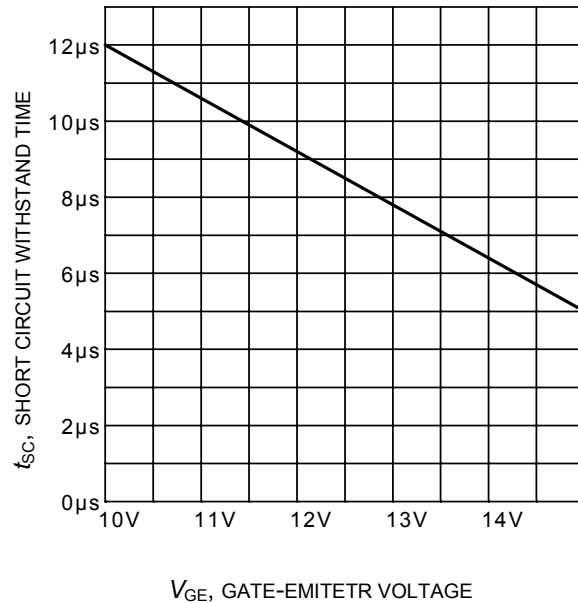
**Figure 17. Typical gate charge**  
( $I_C=4\text{ A}$ )



**Figure 18. Typical capacitance as a function of collector-emitter voltage**  
( $V_{GE}=0\text{V}$ ,  $f=1\text{ MHz}$ )

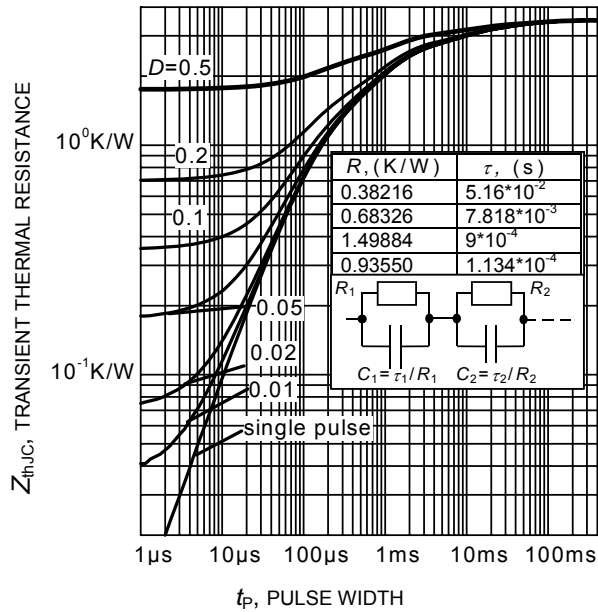


**Figure 19. Typical short circuit collector current as a function of gate-emitter voltage**  
( $V_{CE} \leq 400\text{V}$ ,  $T_j \leq 150^\circ\text{C}$ )

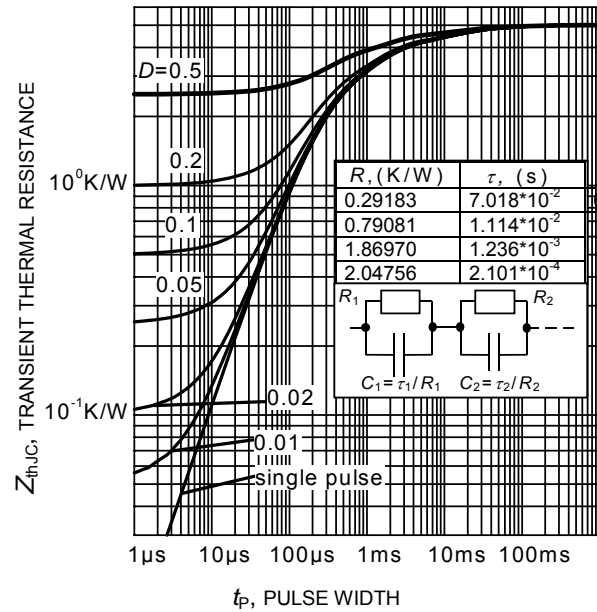


**Figure 20. Short circuit withstand time as a function of gate-emitter voltage**  
( $V_{CE}=600\text{V}$ , start at  $T_j=25^\circ\text{C}$ ,  $T_{jmax}<150^\circ\text{C}$ )

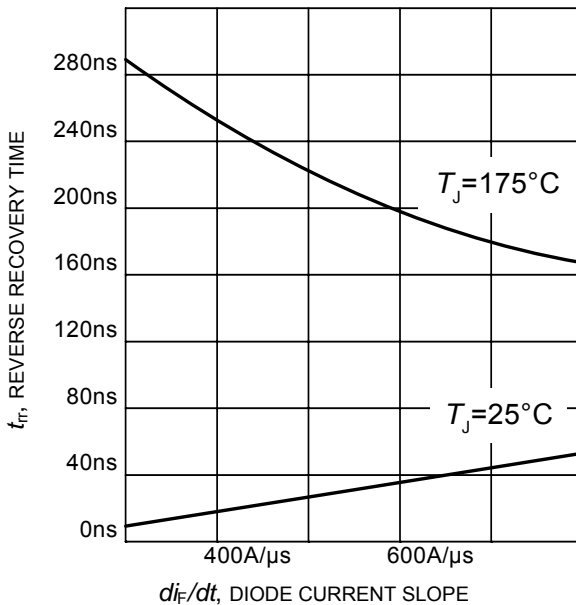




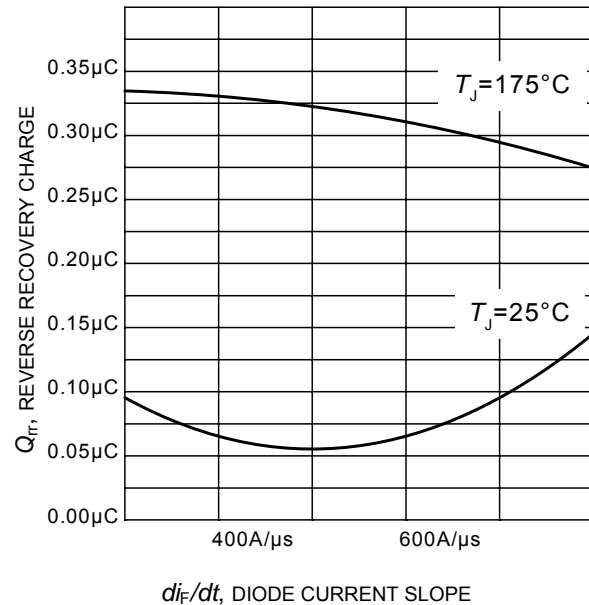
**Figure 21. IGBT transient thermal resistance**  
( $D = t_p / T$ )



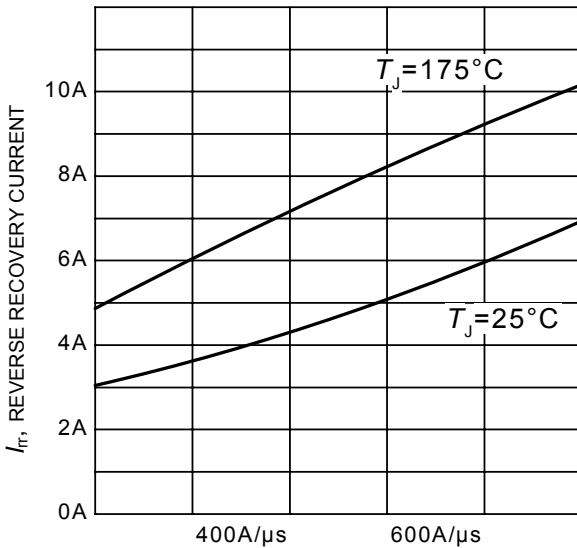
**Figure 22. Diode transient thermal impedance as a function of pulse width**  
( $D = t_p / T$ )



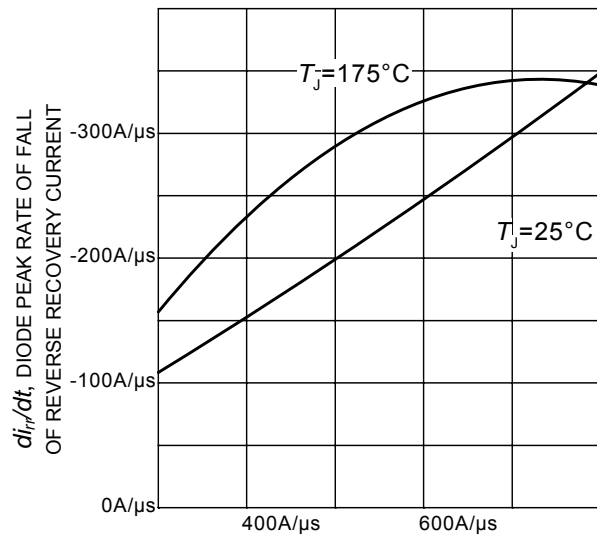
**Figure 23. Typical reverse recovery time as a function of diode current slope**  
( $V_R = 400V$ ,  $I_F = 4A$ ,  
Dynamic test circuit in Figure E)



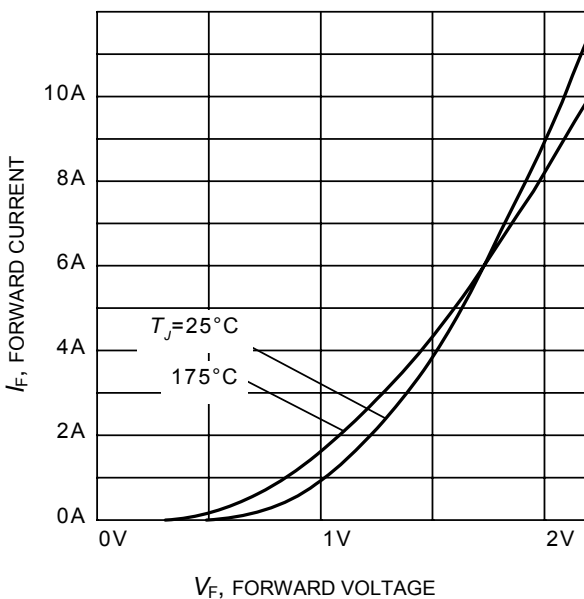
**Figure 24. Typical reverse recovery charge as a function of diode current slope**  
( $V_R = 400V$ ,  $I_F = 4A$ ,  
Dynamic test circuit in Figure E)



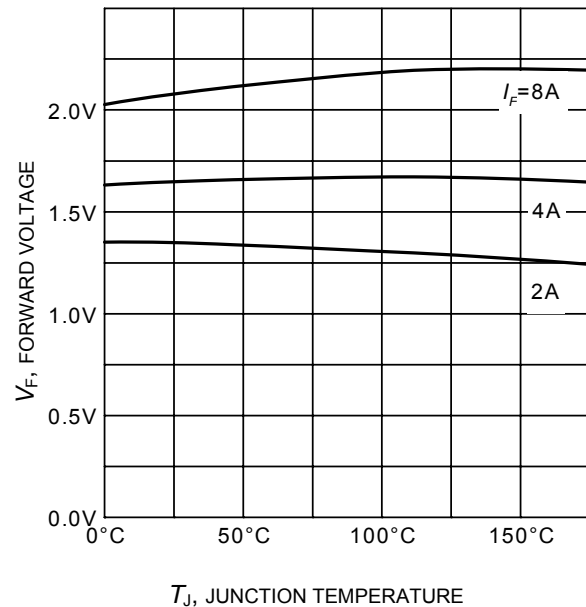
$di_F/dt$ , DIODE CURRENT SLOPE  
**Figure 25. Typical reverse recovery current as a function of diode current slope**  
( $V_R = 400V$ ,  $I_F = 4A$ ,  
Dynamic test circuit in Figure E)



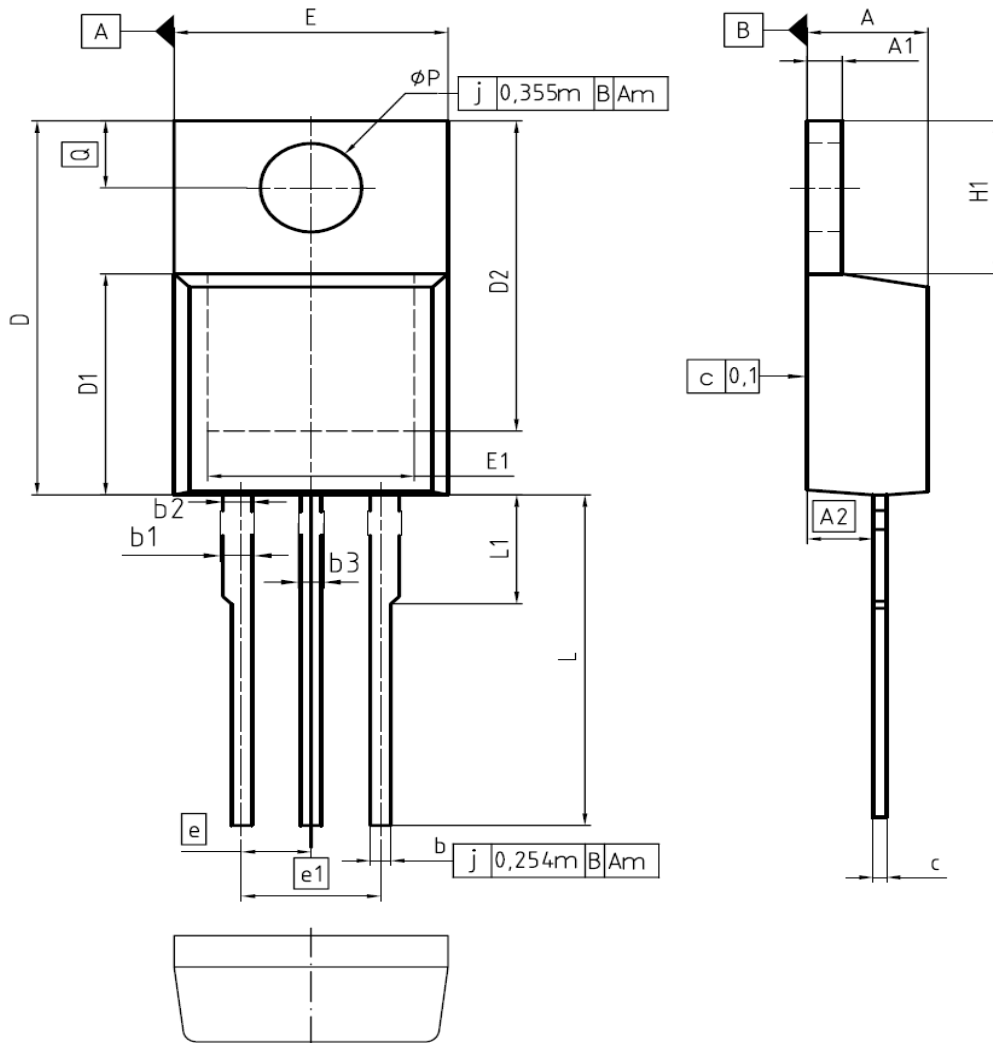
$di_I/dt$ , DIODE CURRENT SLOPE  
**Figure 26. Typical diode peak rate of fall of reverse recovery current as a function of diode current slope**  
( $V_R = 400V$ ,  $I_F = 4A$ ,  
Dynamic test circuit in Figure E)



$I_F$ , FORWARD CURRENT  
**Figure 27. Typical diode forward current as a function of forward voltage**



$V_F$ , FORWARD VOLTAGE  
 $T_J$ , JUNCTION TEMPERATURE  
**Figure 28. Typical diode forward voltage as a function of junction temperature**



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.57	0.169	0.180
A1	1.17	1.40	0.046	0.055
A2	2.15	2.72	0.085	0.107
b	0.65	0.86	0.026	0.034
b1	0.95	1.40	0.037	0.055
b2	0.95	1.15	0.037	0.045
b3	0.65	1.15	0.026	0.045
c	0.33	0.60	0.013	0.024
D	14.81	15.95	0.583	0.628
D1	8.51	9.45	0.335	0.372
D2	12.19	13.10	0.480	0.516
E	9.70	10.36	0.382	0.408
E1	6.50	8.60	0.256	0.339
e	2.54		0.100	
e1	5.08		0.200	
N	3		3	
H1	5.90	6.90	0.232	0.272
L	13.00	14.00	0.512	0.551
L1	-	4.80	-	0.189
øP	3.60	3.89	0.142	0.153
Q	2.60	3.00	0.102	0.118

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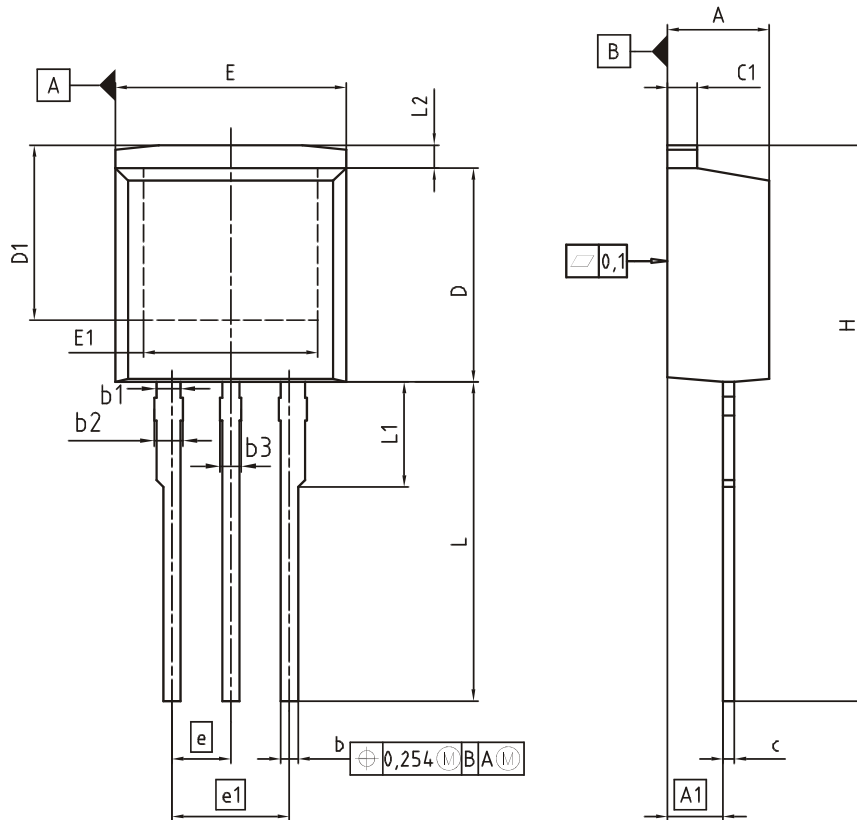
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EUROPEAN PROJECTION

ISSUE DATE  
23-08-2007

REVISION  
05

T0262-3-1 / T0262-3-21



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.300	4.572	0.169	0.180
A1	2.150	2.718	0.085	0.107
b	0.650	0.864	0.026	0.034
b1	0.950	1.093	0.037	0.043
b2	0.950	1.400	0.037	0.055
b3	0.650	1.118	0.026	0.044
c	0.330	0.600	0.013	0.024
c1	1.170	1.400	0.046	0.055
D	8.509	9.450	0.335	0.372
D1	6.900	-	0.272	-
E	9.700	10.363	0.382	0.408
E1	6.500	8.600	0.256	0.339
e	2,540		0,100	
e1	5,080		0,200	
N	3		3	
L	13.000	14.000	0.512	0.551
L1	-	4.800	-	0.189
L2	-	1.727	-	0.068

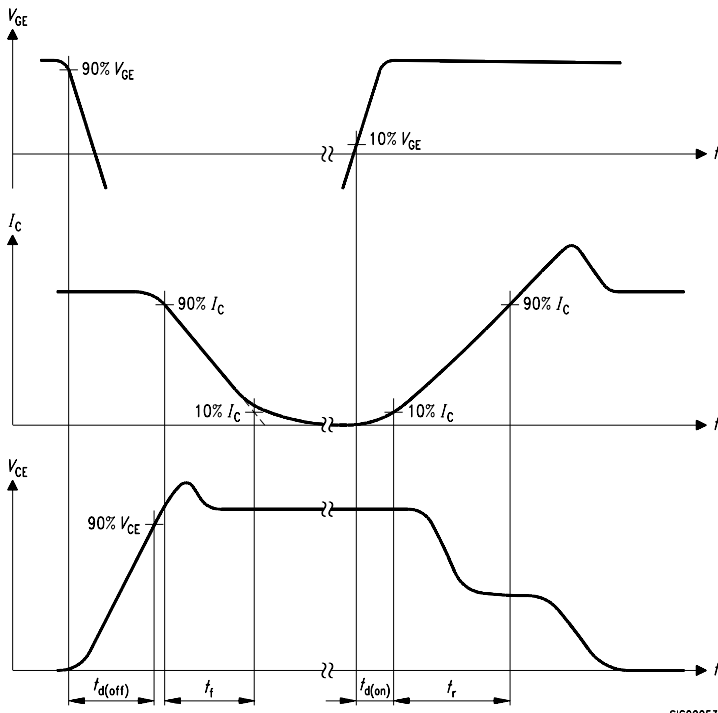
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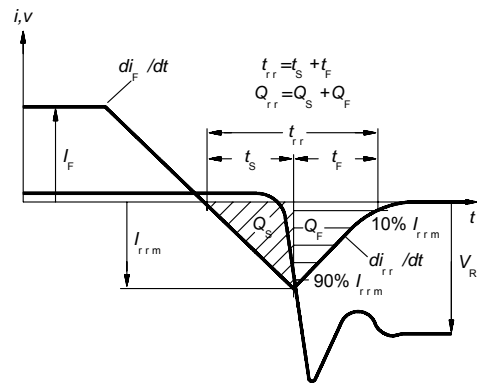
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ISSUE DATE  
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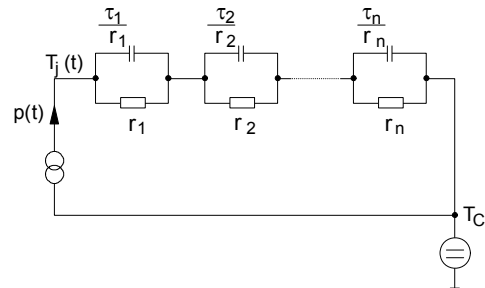
REVISION  
03



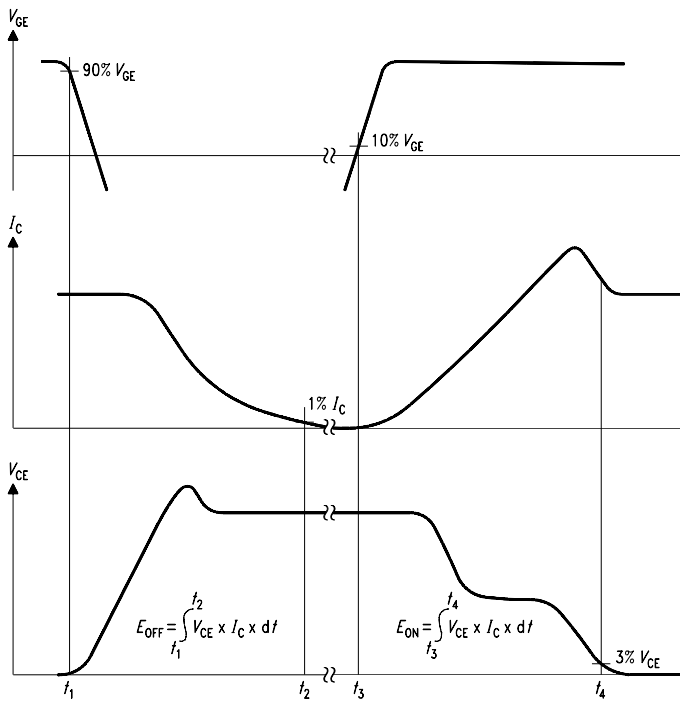
**Figure A. Definition of switching times**



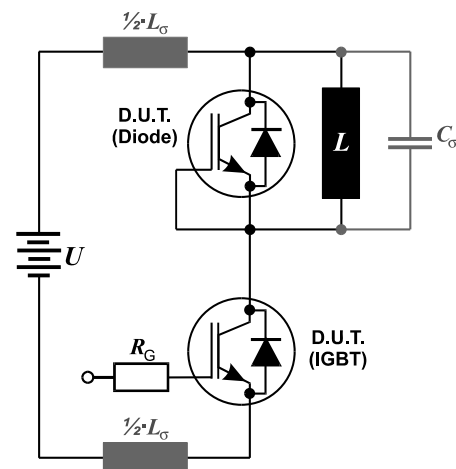
**Figure C. Definition of diodes switching characteristics**



**Figure D. Thermal equivalent circuit**



**Figure B. Definition of switching losses**



**Figure E. Dynamic test circuit**  
Leakage inductance  $L_\sigma = 60\text{nH}$   
and Stray capacity  $C_\sigma = 40\text{pF}$ .

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